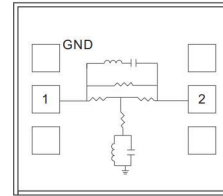


**Performance**

- Frequency: 0.95~2.15GHz
- Insertion Loss:  $\leq 1.0$ dB
- Attenuation: 4.5dB
- Impedance: 50 $\Omega$
- Chip size: 0.82\*1.1\*0.1 mm

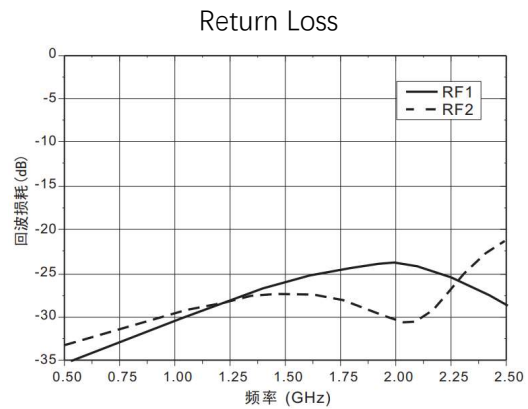
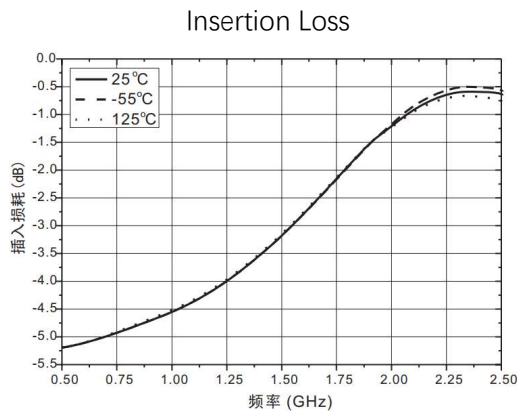
**Function Diagram**



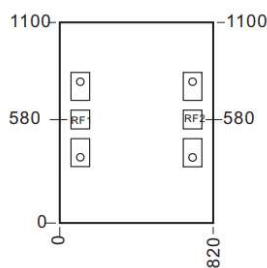
**Electrical Specifications (TA=+25°C, 50 $\Omega$  system)**

Parameter	Min	Typical	Max	Unit
Frequency Range	0.95~2.15			GHz
Insertion Loss	-	0.8	1.0	dB
Attenuation	-	4.5	-	dB
Input Return Loss	20	25	-	dB
Output Return Loss	20	25	-	dB

**Test Curves (Die chip test)**



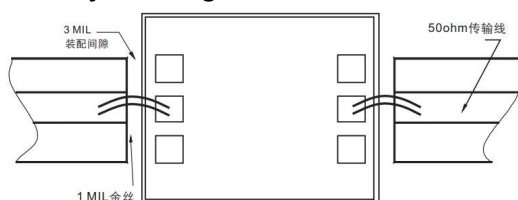
**Outline Size**



**Note:**

1. Unit:  $\mu$ m
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated  
Pads size: 100\*100  $\mu$ m
5. Don't bonding on thru holes
6. Tolerance:  $\pm 50\mu$ m

**Assembly Drawing**



**Bonding Pads Definition**

Number	Symbol	Description
RF1、RF2	RF Ports	RF ports, 50 ohm impedance
	GND	Bottom side of chip must be grounded

**Absolute Max. Ratings**

Static Protection Grade	Class 1A
Input Power	30 dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C



ELECTROSTATIC SENSITIVE DEVICE  
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